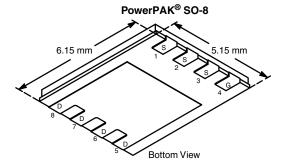


Vishay Siliconix

# N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
	0.0060 at V <sub>GS</sub> = 10 V	60 <sup>a</sup>			
60	0.0075 at V <sub>GS</sub> = 6 V	60 <sup>a</sup>	12 nC		
	0.0095 at V <sub>GS</sub> = 4.5 V	54			



Ordering Information: SiR664DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

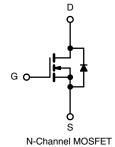
#### **FEATURES**

- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



#### **APPLICATIONS**

- Primary Side Switching
- Synchronous Rectification
- DC/DC Converters
- **Boost Converters**
- DC/AC Inverters



ABSOLUTE MAXIMUM RATINGS (	$T_A = 25  ^{\circ}C$ , unle	ess otherwise no	ted)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		$V_{DS}$	60	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	<b>□</b>
Continuous Drain Current (T <sub>J</sub> = 150 °C)	$T_C = 25 ^{\circ}\text{C}$ $T_C = 70 ^{\circ}\text{C}$	I <sub>D</sub>	60 <sup>a</sup> 54	
	T <sub>A</sub> = 25 °C T <sub>A</sub> = 70 °C	_	21.5 <sup>b, c</sup> 17.2 <sup>b, c</sup>	A
Pulsed Drain Current (t = 100 μs)		I <sub>DM</sub>	150	
Continuous Source-Drain Diode Current	$T_C = 25  ^{\circ}C$ $T_A = 25  ^{\circ}C$	I <sub>S</sub>	60 <sup>a</sup> 4.5 <sup>b, c</sup>	_
Single Pulse Avalanche Current L = 0.1 mH		I <sub>AS</sub>	20	
Single Pulse Avalanche Energy	L=0.11IIII	E <sub>AS</sub>	20	mJ
	T <sub>C</sub> = 25 °C		50 32	
Maximum Power Dissipation	$T_C = 70 ^{\circ}C$ $T_A = 25 ^{\circ}C$	P <sub>D</sub>	5 <sup>b, c</sup>	W
	T <sub>A</sub> = 70 °C		3.2 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>			260	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, f</sup>	t ≤ 10 s	R <sub>thJA</sub>	20	25	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	$R_{thJC}$	2	2.5	] 0/**	

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 70 °C/W.

# SiR664DP

# Vishay Siliconix



<b>SPECIFICATIONS</b> ( $T_J = 25  ^{\circ}C$ ,	unless oth	erwise noted)					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		103		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η – 200 μΑ		- 5.5		IIIV/ C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.3		2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zovo Coto Voltogo Dvoin Cuvvent	1	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0050	0.0060		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 15 A		0.0060	0.0075	Ω	
	, ,	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		0.0073	0.0095		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A		70		S	
Dynamic <sup>b</sup>					<u> </u>		
Input Capacitance	C <sub>iss</sub>			1750			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, f = 1 MHz		720		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			60		ρι	
Tiores Transcer Capacitance	-155	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		26	40		
Total Gate Charge	$Q_{g}$	$V_{DS} = 30 \text{ V}, V_{GS} = 6 \text{ V}, I_{D} = 10 \text{ A}$		16	24		
Total Cara Cara go	·9	105 cc 1, 105 c 1, 10		12	18	-	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		5		nC	
Gate-Drain Charge	Q <sub>gd</sub>	D3 , G3 - , D		3.2			
Output Charge	Q <sub>oss</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V		29	45		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.5	1.7	3	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>		0.0	10	20		
Rise Time	t <sub>r</sub>	$V_{DD} = 30 \text{ V, R}_{L} = 3 \Omega$		12	24		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_q = 1 \Omega$		24	48		
Fall Time	t <sub>f</sub>	g all all all all all all all all all al		7	14		
Turn-On Delay Time	t <sub>d(on)</sub>			34	68	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_{I}$ = 3 $\Omega$		95	190		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		20	40		
Fall Time	t <sub>f</sub>	GEN - , GEN		8	16	-	
Drain-Source Body Diode Characteristic					10		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			60		
Pulse Diode Forward Current ( $t_p = 100 \mu s$ )	I <sub>SM</sub>	0 == -			150	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 5 A		0.76	1.1	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	.3 57.		29	55	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			19	35	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		14	33	ns	
<u> </u>				-			
Reverse Recovery Rise Time	t <sub>b</sub>			15			

#### Notes:

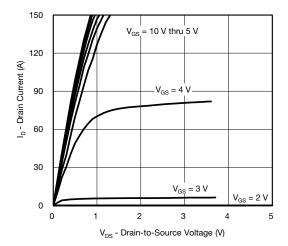
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

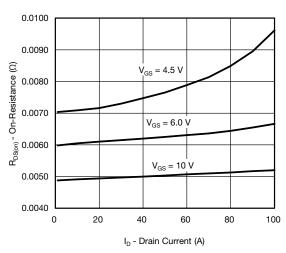
b. Guaranteed by design, not subject to production testing.



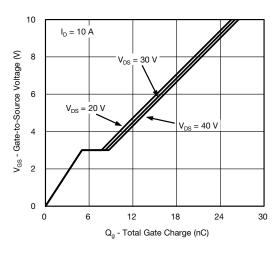
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



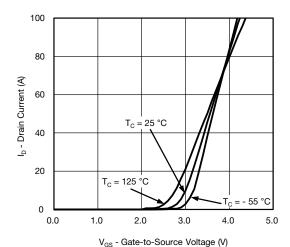
#### **Output Characteristics**



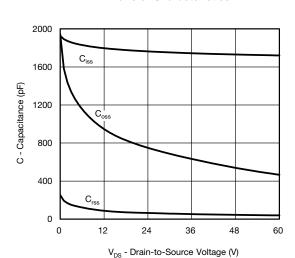
#### On-Resistance vs. Drain Current



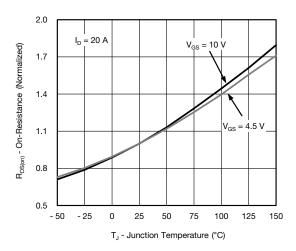
**Gate Charge** 



**Transfer Characteristics** 



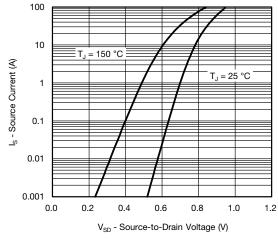
Capacitance

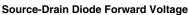


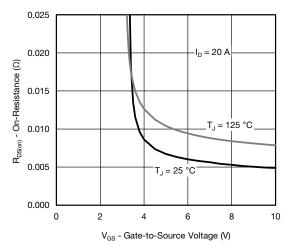
On-Resistance vs. Junction Temperature

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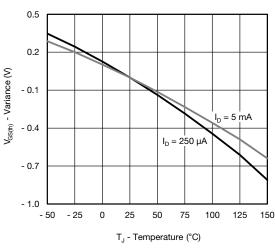
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



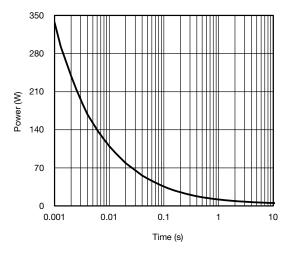




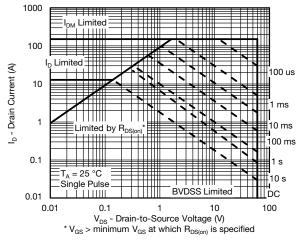
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



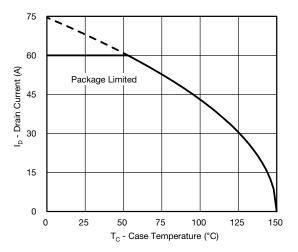
Single Pulse Power, Junction-to-Ambient



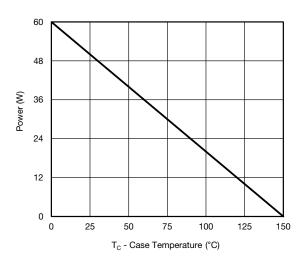
Safe Operating Area, Junction-to-Ambient



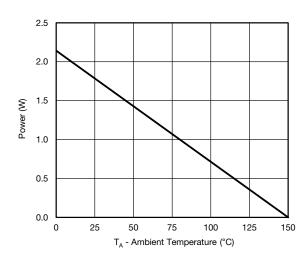
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### **Current Derating\***







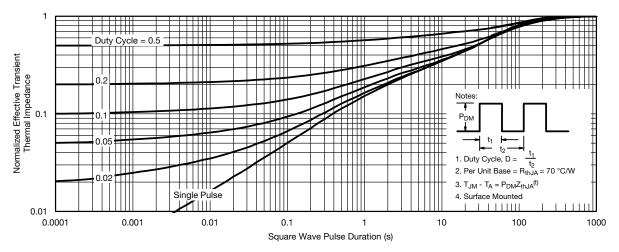
Power, Junction-to-Ambient

<sup>\*</sup> The power dissipation PD is based on TJ(max) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

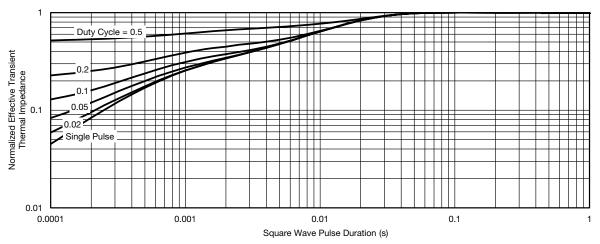
# Vishay Siliconix



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



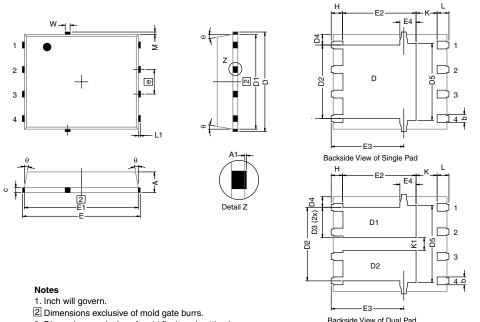
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62849



DWG: 5881

# PowerPAK® SO-8, (Single/Dual)



	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.97	1.04	1.12	0.038	0.041	0.044	
A1		-	0.05	0	-	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.56	3.76	3.91	0.140	0.148	0.154	
D3	1.32	1.50	1.68	0.052	0.059	0.066	
D4	0.57 typ.			0.0225 typ.			
D5	3.98 typ.			0.157 typ.			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	5.79	5.89	5.99	0.228	0.232	0.236	
E2 (for AL product)	3.30	3.48	3.66	0.130	0.137	0.144	
E2 (for other product)	3.48	3.66	3.84	0.137	0.144	0.151	
E3	3.68	3.78	3.91	0.145	0.149	0.154	
E4 (for AL product)	0.58 typ.			0.023 typ.			
E4 (for other product)		0.75 typ.		0.030 typ.			
е	1.27 BSC			0.050 BSC			
K (for AL product)		1.45 typ.		0.057 typ.			
K (for other product)	1.27 typ.			0.050 typ.			
K1	0.56	-	-	0.022	-	-	
Н	0.51	0.61	0.71	0.020	0.024	0.028	
L	0.51	0.61	0.71	0.020	0.024	0.028	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М	0.125 typ.			0.005 typ.			

Revison: 20-May-13 Document Number: 71655



## RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000

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Vishay:

SIR664DP-T1-GE3